

Amendments to the Claims:

The following listing of claims will replace all prior versions and/or listings of claims in the application.

Listing of Claims:

Claims 1-23 (Cancelled).

24. (Currently amended) An assembly, comprising:
- a circuit board including an electrically conductive contact coupled to the circuit board;
 - an electronic component coupled to the circuit board;
 - an electrically conductive shielding portion in thermal contact with the electronic component;
 - a biasing element coupled to the electrically conductive shielding portion;
 - ~~an~~ a first electrically conductive connection member in contact with the biasing element and in electrical communication with the electrically conductive shielding portion; and
 - wherein the biasing element resiliently biases the first electrically conductive connection member onto the electrically conductive contact forming a solder-less detachable electrical connection between the first electrically conductive connection member and the electrically conductive contact.
25. (Currently amended) The assembly of claim 24, wherein a surface of the shielding portion defines a cavity for receiving at least one electrically conductive connection member; wherein the at least one electrically conductive connection member includes the first electrically conductive connection member.

26. (Previously presented) The assembly of claim 25, the shielding portion having a plurality of cooling members extending away therefrom, wherein at least one cooling member accommodates the cavity.
27. (Previously presented) The assembly of claim 24, further comprising a mounting strut for mounting the shielding portion on the circuit board.
28. (Currently amended) The assembly of claim 24 comprising a plurality of ~~said~~ electrically conductive connection members arranged to extend along a peripheral edge of the electronic component to form a shielding cage around the electronic component; wherein the plurality of electrically conductive connection members includes the first electrically conductive connection member.
29. (Currently amended) The assembly of claim 28 further comprising one or more support members, each support member being attached to at least two electrically conductive connection members of the plurality of electrically conductive connection members.
30. (Previously presented) The assembly of claim 29, wherein the one or more support members are electrically conductive.
31. (Currently amended) The assembly of claim 24, wherein at least one of the electrically conductive shielding portion and the first ~~said at least one~~ electrically conductive connection member are metal.
32. (Previously presented) The assembly of claim 24, wherein the biasing element is a spring.

33. (Previously presented) The assembly of claim 24, wherein the biasing element comprises at least two parts.
34. (Currently amended) An electromagnetic (EM) shielding assembly for shielding an electronic component mounted on a circuit board, the assembly comprising:
an electrically conductive shielding portion mountable in thermal contact with the electronic component;
a biasing element coupled to the electrically conductive shielding portion;
~~an~~ a first electrically conductive connection member in contact with the biasing element and in electrical communication with the electrically conductive shielding portion;
wherein the biasing element is configured to resiliently bias the first electrically conductive connection member onto an electrically conductive contact on the circuit board to form a solder-less detachable electrical connection between the first electrically conductive connection member and the electrically conductive contact when the electrically conductive shielding portion is mounted in thermal contact with the electronic component.
35. (Currently amended) The assembly apparatus of claim 34, further comprising an opening in the circuit board in which said first electrically conductive connection member is received, an interior surface of the opening being coated with an electrically conductive layer forming said electrically conductive contact.
36. (Currently amended) The assembly apparatus of claim 34, comprising a plurality of said electrically conductive connection members, each connection member bearing down upon the electrically conductive contact; wherein the plurality of electrically conductive connection members includes the first electrically conductive connection member.
37. (Currently amended) The assembly apparatus of claim 34, the circuit board having a plurality of said electrically conductive contacts, the EM shielding assembly comprising a

plurality of ~~said~~ electrically conductive connection members, each electrically conductive connection member bearing down upon a respective one of the electrically conductive contacts;

wherein the plurality of electrically conductive connection members includes the first electrically conductive connection member.

38. (Currently amended) The apparatus of claim 34, wherein the first electrically conductive connection member comprises at least two parts.

39. (Currently amended) A method for providing electromagnetic (EM) shielding for an electronic component mounted on a circuit board, the circuit board comprising an electrically conductive contact for providing a connection to a predetermined voltage, the method comprising:

providing an EM shielding assembly comprising an electrically conductive shielding portion and at least one resiliently biased electrically conductive connection member in electrical communication with the shielding portion; ~~and~~

mounting the shielding portion on the electronic component such that the shielding portion at least partially surrounds the component; and

resiliently biasing the at least one electrically conductive connection member onto the electrically conductive contact to form a solder-less detachable electrical connection between the at least one electrically conductive connection member and the electrically conductive contact.

40. (Currently amended) The method of claim 39, wherein a surface of the shielding portion defines a cavity for receiving one of the at least one electrically conductive connection members.

41. (Previously presented) The method of claim 39, the shielding portion having a plurality of cooling members extending away therefrom, wherein at least one cooling member accommodates the cavity.
42. (Currently amended) An apparatus, comprising:
a substrate, wherein the substrate comprises at least one electrically conductive contact;
an integrated circuit coupled to the substrate;
an electrically conductive shield mountable adjacent the integrated circuit;
a biasing element coupled to the electrically conductive shield; and
a connection member in contact with the biasing element, wherein the connection member is resiliently biased onto the electrically conductive contact by the biasing element and wherein the connection member forms a detachable electrical connection between the electrically conductive shield and the electrically conductive contact.
43. (Previously presented) The apparatus of claim 42, wherein the biasing element is a spring, and wherein the biasing element compresses as the connection member is biased onto the electrically conductive contact.
44. (Previously presented) An assembly, comprising:
a circuit board including an electrically conductive contact coupled to the circuit board;
a substrate coupled to the circuit board;
an electronic component coupled to the substrate;
an electrically conductive shielding portion in thermal contact with the electronic component;
an electrically conductive connection member, comprising a first piece and a second piece with a biasing element between the first piece and the second piece, coupled to the electrically conductive shielding portion through the first piece; and

wherein the biasing element resiliently biases the first piece and second piece apart to bias the second piece onto the electrically conductive contact to form a solder-less detachable electrical connection between the electrically conductive connection member and the electrically conductive contact.